

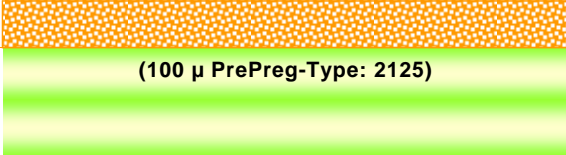
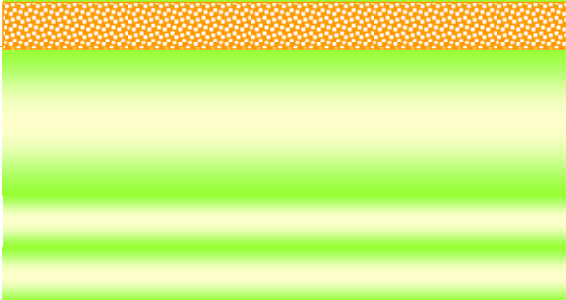

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

**03 111 FR4 35 L61.35 P10 s1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**03\_111\_FR4\_35\_L61.35\_p10\_s16**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		} <b>A1</b> } <b>B</b>
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	610 $\mu$	L-FR4		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-99</b>	35 $\mu$	Copper		

© Copyright by Printed Circuit Boards GmbH